



## Material Content Data Sheet



<b>Sales Product Name</b>		IPN80R750P7		<b>Issued</b>		1. August 2018		
<b>MA#</b>		MA001730334						
<b>Package</b>		PG-SOT223-3-1		<b>Weight*</b>		116.96 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.170	1.86	1.86	18555	18555
leadframe	inorganic material	phosphorus	7723-14-0	0.016	0.01		134	
	non noble metal	iron	7439-89-6	0.052	0.04		448	
	non noble metal	copper	7440-50-8	52.304	44.71	44.76	447193	447775
	non noble metal	copper	7440-50-8	0.251	0.22	0.22	2150	2150
wire	non noble metal	copper	7440-50-8	0.251	0.22	0.22	2150	2150
encapsulation	organic material	carbon black	1333-86-4	0.175	0.15		1498	
	plastics	epoxy resin	-	6.833	5.84		58421	
	inorganic material	silicondioxide	60676-86-0	51.393	43.94	49.93	439408	499327
leadfinish	non noble metal	tin	7440-31-5	1.352	1.16	1.16	11560	11560
plating	noble metal	silver	7440-22-4	0.220	0.19	0.19	1885	1885
solder	non noble metal	tin	7440-31-5	0.044	0.04		375	
	noble metal	silver	7440-22-4	0.055	0.05		469	
	non noble metal	lead	7439-92-1	2.094	1.79	1.88	17904	18748
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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